

Lonten N-channel 40V, 80A, 5.0mΩ Power MOSFET

Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- $40V,80A,R_{DS(ON).max}=5.0m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- Green device available

Applications

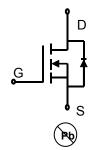
- Motor Drives
- ◆ UPS
- ♦ DC-DC Converter

Product Summary

 $\begin{array}{ll} V_{DSS} & 40V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} = 10V & 5.0 m\Omega \\ I_D & 80A \end{array}$

Pin Configuration





N-Channel MOSFET

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	40	V	
Continuous drain current (Tc = 25°C)		80	A	
Continuous drain current (Tc = 100°C)	I _D	51	Α	
Pulsed drain current ¹⁾	Ірм	320	A	
Gate-Source voltage	V _{GSS}	±20	V	
Avalanche energy ²⁾	E _{AS}	156	mJ	
Power Dissipation (T _C = 25°C)	P _D	54	W	
Storage Temperature Range	T _{STG}	-55 to +150	°C	
Operating Junction Temperature Range	TJ	-55 to +150	°C	

Thermal Characteristics

Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R _в ус	2.3	°C/W	



Package Marking and Ordering Information

Device	Device Package	Marking
LNN04R050	DFN5×6	LNN04R050

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter	Symbol	ymbol Test Condition		Тур.	Max.	Unit	
Static characteristics	'			1	•		
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	40			V	
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0		2.0	V	
		V _{DS} =40 V, V _{GS} =0 V, T _J = 25°C			1 μΑ		
Drain-source leakage current	I _{DSS}	V _{DS} =32 V, V _{GS} =0 V, T _J = 125°C			30	μA	
Gate leakage current, Forward	Igssf	V _{GS} =20 V, V _{DS} =0 V			100	nA	
Gate leakage current, Reverse	Igssr	V _{GS} =-20 V, V _{DS} =0 V			-100	nA	
Drain course en etete registence		V _{GS} =10 V, I _D =20 A		3.8	5	mΩ	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =4.5 V, I _D =10 A		4.7	1.7 6.2 m		
Forward transconductance	g fs	V _{DS} =5 V , I _D =30 A		79		S	
Dynamic characteristics							
Input capacitance	C _{iss}			4023.6			
Output capacitance	Coss	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V},$ $V_{DS} = 1 \text{ MHz}$		410.4		pF	
Reverse transfer capacitance	Crss	T - IIVINZ		338.5			
Turn-on delay time	t _{d(on)}			231.6		- ns	
Rise time	t _r	$V_{DD} = 30V, V_{GS} = 15V, I_D = 30 A$		213.6			
Turn-off delay time	t _{d(off)}	VDD - 30V,VGS-13V, ID -30 A		219.2			
Fall time	t _f			74			
Gate resistance	Rg	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.4		Ω	
Gate charge characteristics							
Gate to source charge	Q _{gs}	V 00 V 1 00 A		11			
Gate to drain charge	Q _{gd}	V _{DS} =30 V, I _D =30A,		16.7		nC	
Gate charge total	Qg	- V _{GS} =10V		66.7			
Drain-Source diode characteristi	cs and Maxi	mum Ratings				•	
Continuous Source Current	Is				80	Α	
Pulsed Source Current ³⁾	I _{SM}				320	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =40A, T _J =25℃			1.2	V	
Reverse Recovery Time	trr	1 -200 di/dt-1000///- T -25°0		41.4		ns	
Reverse Recovery Charge	Qrr	I _S =20A,di/dt=100A/us, T _J =25℃		29		nC	

Notes:

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2: V_{DD} =25V, V_{GS} =10V, L=0.5mH, I_{AS}=25A, R_G=25 Ω , Starting T_J=25 $^{\circ}$ C.
- 3: Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

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Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

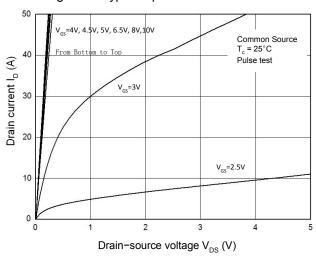


Figure 2. Transfer Characteristics

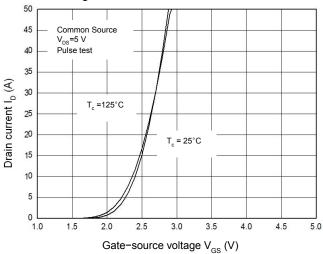


Figure 3. Capacitance Characteristics

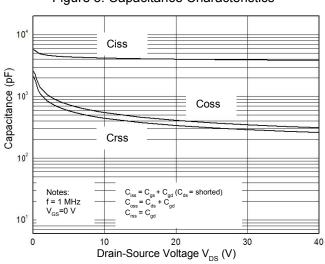


Figure 4. Gate Charge Waveform

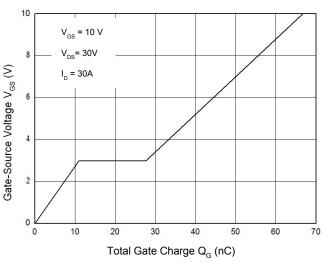


Figure 5. Body-Diode Characteristics

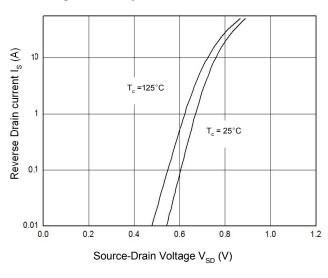


Figure 6. Rdson-Drain Current

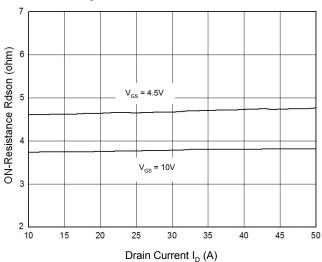
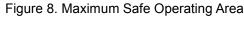
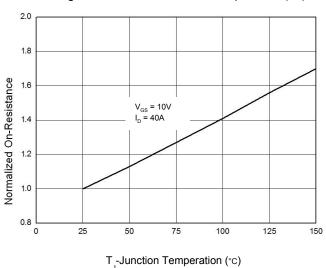




Figure 7. Rdson-Junction Temperature ($^{\circ}$ C)





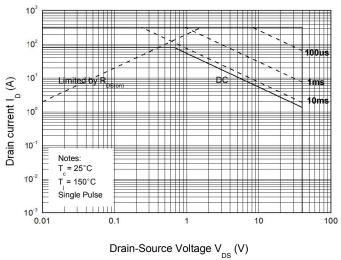
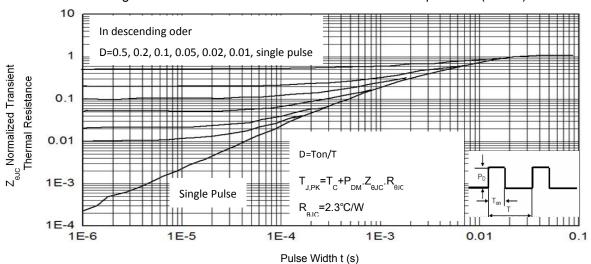


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)

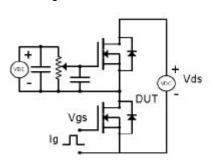


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Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform



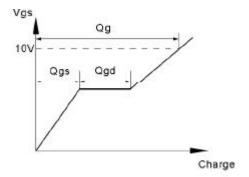
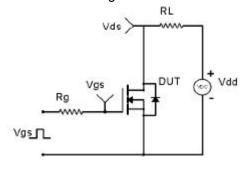


Figure 9. Resistive Switching Test Circuit & Waveforms



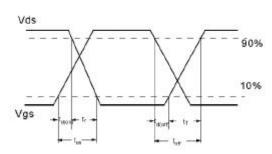
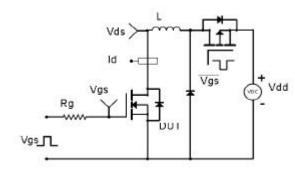


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



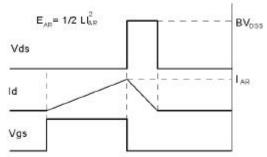
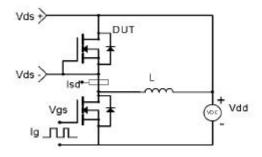
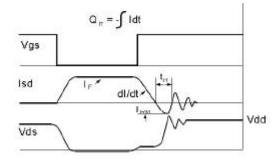


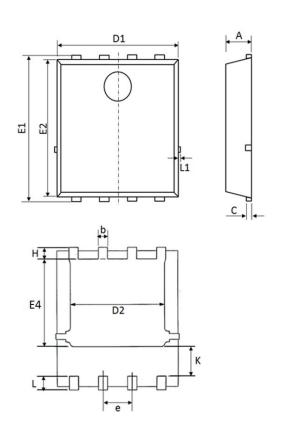
Figure 11. Diode Recovery Circuit & Waveform





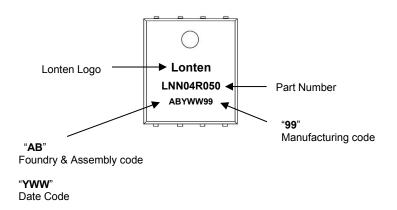


Mechanical Dimensions for DFN5×6



COMMON DIMENSIONS						
SYMBOL	MILLIMETERS			INCHS		
STIVIBOL	MIN	NOM	MAX	MIN	NOM	MAX
А	1	1.1	1.2	0.039	0.043	0.047
b	0.3	0.4	0.5	0.012	0.016	0.020
С	0.154	0.254	0.354	0.006	0.010	0.014
D1	5	5.2	5.4	0.197	0.205	0.213
D2	3.8	4.1	4.25	0.150	0.161	0.167
E1	5.95	6.15	6.35	0.234	0.242	0.250
E2	5.66	5.86	6.06	0.223	0.231	0.239
E4	3.52	3.72	3.92	0.139	0.146	0.154
е	1.27 BSC			0.050 BSC		
Н	0.4	0.5	0.6	0.016	0.020	0.024
L	0.5	0.6	0.7	0.020	0.024	0.028
L1	-	-	0.12	-	-	0.005
К	1.14	1.29	1.44	0.045	0.051	0.057

DFN5×6 Part Marking Information





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